

REMARKS

The present invention relates to an adhesive label comprising a circuit substrate, electronic components formed on at least one surface of said circuit substrate, and an adhesive layer on said electronic components.

The Examiner has not explicitly indicated that the drawings submitted on April 30, 2001 have been accepted. Applicants respectfully request the Examiner make such an acknowledgment. Applicants submit herewith a proposed drawing correction, wherein Fig. 3 has been amended to recite --Prior Art-- (highlighted), to clearly indicate that Fig. 3 is directed to the structure of a typical conventionally used adhesive label-type data carrier. Such an amendment is supported by the specification at, for example, pages 1 to 4.

In this Amendment, claim 1 has been amended to recite --electronic components formed on at least one surface of said circuit substrate--. This amendment is supported by the specification at, for example, page 6, 1st full paragraph and original claim 6.

Claims 4 and 6 have been amended to replace the language “an entire contactless data carrier element” with --an entire data carrier element for a contactless data carrier system--. Such an amendment is supported by the specification at, for example, page 1, 2nd full paragraph.

Claim 5 has been amended to be in proper dependent form. Claim 6 has been amended to be dependent from claim 1. Claims 1, 4, 5 and 6 have also been amended to improve the

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grammatical format. These amendments are made for clarification purposes only, and are not be deemed to narrow the scope of the present invention.

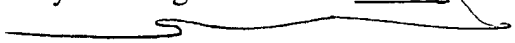
Claim 7 has been added as a new claim. This new claim is supported by original claim 5.

No new matter has been added, and thus entry of the Amendment is respectfully submitted to be proper. Upon entry of the Amendment, claims 1-7 are all of the claims pending in the application.

In Paragraph No. 3, page 2 of the Office Action, claims 1-6 were rejected under 35 U.S.C. §112, second paragraph, as allegedly being indefinite.

Applicants respectfully submit that claims 1-6 as amended are not indefinite. In this Amendment, Applicants have amended claim 1 to delete “characterized by” and “for applying to an article” as suggested by the Examiner. Claim 1 has also been amended to replace “which” with --wherein said electronic components--.

Regarding claim 3, it is clear from Applicants’ specification that the “support sheet” is not the same as the “circuit substrate” in claim 1. The “support sheet” is one component of a double-coated adhesive layer. See, 1st full paragraph on page 9. In addition, Applicants have amended claim 3 to replace “a double-coated adhesive layer having an adhesive layer on each side of a support sheet” with --a double-coated adhesive layer having an adhesive coating on



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each side of a support sheet-- to distinguish this adhesive layer from the one referred to in the same claim.

Regarding the term “contactless” in claims 4 and 6, Applicants have amended these claims to replace the language “an entire contactless data carrier element” with --an entire data carrier element for a contactless data carrier system--.

Claim 5 has been amended to correct improper dependent form, and to replace “a reverse side” with --on the reverse side-- as suggested by the Examiner.

In view of the above, the Examiner is respectfully requested to reconsider and withdraw the §112, second paragraph rejection.

In Paragraph No. 5, page 3 of the Office Action, claims 1-5 were rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over Applicants’ “admitted prior art” in view of Tanimura et al (U.S. Patent No. 6,065,701).

Applicants respectfully traverse the rejection because the present invention is not *prima facie* obvious over the cited references, and accordingly, submit that the rejection should be withdrawn.

Tanimura discloses a label body comprising a coated layer, a pressure sensitive adhesive, reinforcing material, a pressure sensitive adhesive, electronic components, a polyimide substrate, and both faces adhesive material, in this order (Fig. 2 of Tanimura).

A typical conventionally used adhesive label-type data carrier comprises a surface layer, a resin layer, electronic components, a circuit substrate and an adhesive layer, in this order (page 1 and Fig. 3 of Applicants' specification) and alternatively, electronic components being separately formed on each side of the circuit substrate and connected via a through-hole (page 2).

On the other hand, the present invention is directed to a label body comprises a circuit substrate, electronic components formed on at least one surface of said circuit substrate, and an adhesive layer formed on said electronic components (Fig. 1). The present invention is also directed to a label body containing an additional surface layer on a circuit substrate surface that is on the reverse side with respect to a surface carrying said electronic components (Fig. 2).

Tanimura does not teach or suggest embedding electronic components in an adhesive layer. In Tanimura, an opening is formed in the reinforcing material (14) at a position overlying the IC20 to absorb the thickness of the IC20 (column 3, lines 60-64 and Fig. 2). Therefore, the adhesive layer (15) is used simply to adhere the reinforcing material and the polyimide substrate, and it does not embed the electronic components.

Further, Tanimura teaches three adhesive layers in a label body: two are pressure sensitive (layers 13 and 15, Fig.2), and the third, which is to be applied to an article surface, is both faces adhesive (layer 17, Fig.2). However, Tanimura does not teach or suggest the use of pressure sensitive adhesive material for layer 17 as presently claimed.

Accordingly, even if there might be a suggestion or motivation to modify a conventional adhesive label with the structure of Tanimura, the combination would not result in the present invention.

In view of the above, the Examiner is respectfully requested to reconsider and withdraw the §103(a) rejection, and allow claims 1-7.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the local Washington, D.C. telephone number listed below.

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The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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PATENT TRADEMARK OFFICE

Date: April 29, 2003

APPENDIX
VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

The claims are amended as follows:

1. (amended) An adhesive label ~~characterized by~~ comprising a circuit substrate, electronic components formed on at least one surface of said circuit substrate, and an adhesive layer on said electronic components ~~for applying to an article, which wherein said electronic components~~ are sequentially laminated and said adhesive layer is to be applied to an article.

3. (amended) The adhesive label according to claim 1, wherein said adhesive layer is a double-coated adhesive layer having an adhesive layer coating on each side of a support sheet.

4. (amended) The adhesive label according to any one of claims 1 to 3, wherein an entire ~~contactless data carrier element~~ for a contactless data carrier system containing said electronic components is ~~carried formed~~ on one side of said circuit substrate, and said adhesive layer ~~for applying on an article is formed on said entire contactless data carrier element.~~

5. (amended) The adhesive label according to any one of claims 1 to [4]3, wherein a surface layer is provided on a circuit substrate surface that is ~~a~~ on the reverse side to a surface carrying said electronic element.

6. (amended) The adhesive label according to claim ~~5~~1, wherein said electronic components are separately formed on each surface of said circuit substrate and connected ~~with to~~

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each other by a through-hole to integrate both electronic components to form an entire
~~contactless data carrier element~~ for a contactless data carrier system, said adhesive layer ~~for~~
~~applying to an article~~ is formed on one of said separately formed electronic components, and said
surface layer is formed on the other of said separately formed electronic components.

Claim 7 is added as a new claim.

FIG. 1

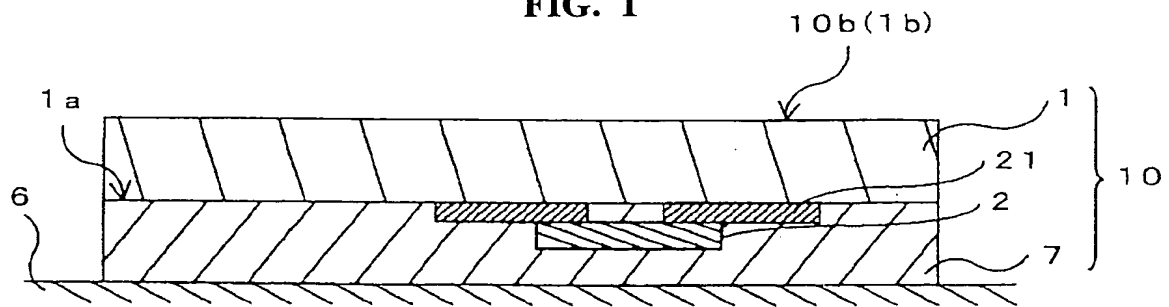


FIG. 2

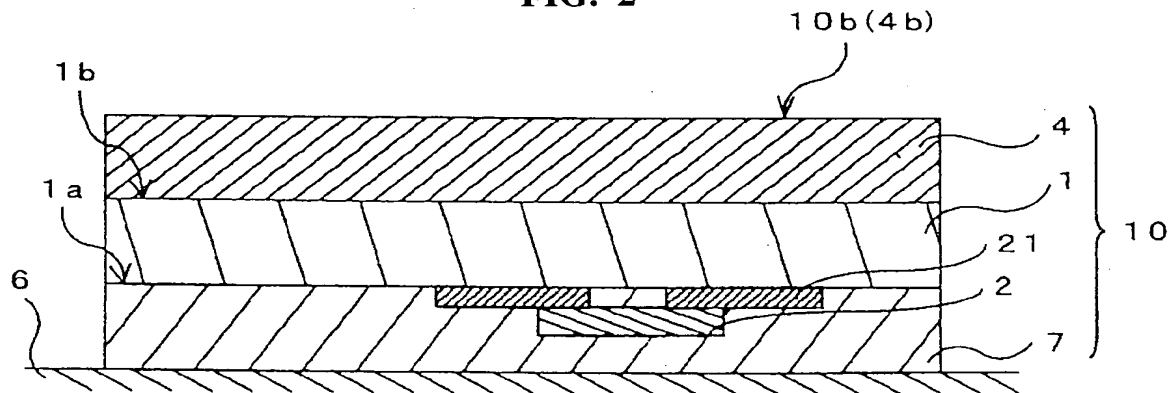


FIG. 3

Prior Art

